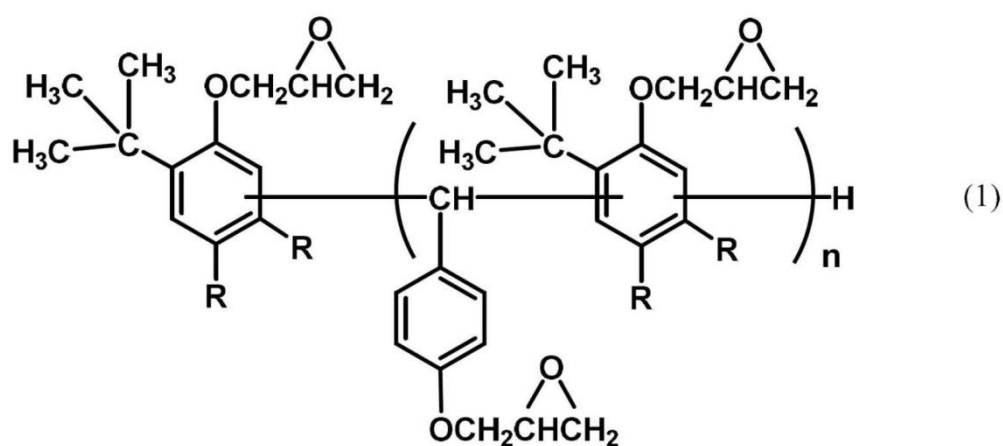


EPOXY RESIN, CURABLE RESIN COMPOSITION, AND CURED OBJECT
THEREFROM

5

[ABSTRACT]

The present invention provides an epoxy resin and a curable resin composition from which a cured object has excellent heat resistance and tracking resistance properties. An epoxy resin represented by the following Formula (1) and having a value
10 obtained by dividing the epoxy equivalent (g/eq.) by a softening point (°C) of 2.0 or more and less than 2.2:



in Formula (1), a plurality of R's are present independently and each represents a methyl group or a hydrogen atom, and n is an average number of repetitions, and a real number
15 of 1 to 10.

FIG. 1